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# FDS6690A

# Single N-Channel, Logic-Level, PowerTrench® MOSFET

# **General Description**

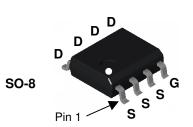
This N-Channel Logic Level MOSFET is produced using Fairchild Semiconductor's advanced PowerTrench process that has been especially tailored to minimize the on-state resistance and yet maintain superior switching performance.

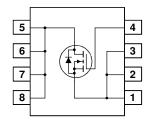
These devices are well suited for low voltage and battery powered applications where low in-line power loss and fast switching are required.



## **Features**

- 11 A, 30 V.  $R_{DS(ON)} \, = 12.5 \; m\Omega \; @ \; V_{GS} = 10 \; V$   $R_{DS(ON)} \, = 17.0 \; m\Omega \; @ \; V_{GS} = 4.5 \; V$
- · Fast switching speed
- · Low gate charge
- High performance trench technology for extremely low Rps/ONL
- · High power and current handling capability





# Absolute Maximum Ratings T<sub>A</sub>=25°C unless otherwise noted

| Symbol                            | Parameter  |           | Ratings     | Units |
|-----------------------------------|--|-----------|-------------|-------|
| V <sub>DSS</sub>                  | Drain-Source Voltage                             |           | 30          | V     |
| V <sub>GSS</sub>                  | Gate-Source Voltage                              |           | ±20         | V     |
| I <sub>D</sub>                    | Drain Current - Continuous                       | (Note 1a) | 11          | Α     |
|                                   | - Pulsed   |           | 50          |       |
| P <sub>D</sub>                    | Power Dissipation for Single Operation           | (Note 1a) | 2.5         | W     |
|                                   |  | (Note 1b) | 1.0         |       |
| E <sub>AS</sub>                   | Single Pulse Avalanche Energy                    | (Note 3)  | 96          | mJ    |
| T <sub>J</sub> , T <sub>STG</sub> | Operating and Storage Junction Temperature Range |           | -55 to +150 | °C    |

# **Thermal Characteristics**

| R <sub>eJA</sub> | Thermal Resistance, Junction-to-Ambient | (Note 1a) | 50  | °C/W |
|------------------|---|-----------|-----|------|
| R <sub>θJA</sub> | Thermal Resistance, Junction-to-Ambient | (Note 1b) | 125 |      |
| R <sub>eJC</sub> | Thermal Resistance, Junction-to-Case    | (Note 1)  | 25  |      |

**Package Marking and Ordering Information** 

| Device Marking | Device   | Reel Size | Tape width | Quantity   |
|----------------|----------|-----------|------------|------------|
| FDS6690A       | FDS6690A | 13"       | 12mm       | 2500 units |

| Symbol                                      | Parameter   | Test Conditions  | Min | Тур                 | Max                  | Units |
|---|---|--|-----|---------------------|----------------------|-------|
| Off Char                                    | acteristics                                       |  | 1   | 1                   |                      | 1     |
| BV <sub>DSS</sub>                           | Drain-Source Breakdown Voltage                    | $V_{GS} = 0 \text{ V}, \qquad I_D = 250  \mu\text{A}$  | 30  |                     |                      | V     |
| <u>ΔBV<sub>DSS</sub></u><br>ΔT <sub>J</sub> | Breakdown Voltage Temperature<br>Coefficient      | $I_D$ = 250 $\mu$ A, Referenced to 25°C  |     | 25                  |                      | mV/°C |
| I <sub>DSS</sub>                            | Zero Gate Voltage Drain Current                   | V <sub>DS</sub> = 24 V, V <sub>GS</sub> = 0 V  |     |                     | 1                    | μΑ    |
|   |   | $V_{DS} = 24 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55^{\circ}\text{C}$  |     |                     | 10                   | μΑ    |
| I <sub>GSS</sub>                            | Gate-Body Leakage                                 | $V_{GS} = \pm 20 \text{ V},  V_{DS} = 0 \text{ V}$   |     |                     | ±100                 | nA    |
| On Chara                                    | acteristics (Note 2)                              |  |     |                     |                      |       |
| V <sub>GS(th)</sub>                         | Gate Threshold Voltage                            | $V_{DS} = V_{GS}$ , $I_D = 250 \mu A$  | 1   | 1.9                 | 3                    | V     |
| $\frac{\Delta V_{GS(th)}}{\Delta T_J}$      | Gate Threshold Voltage<br>Temperature Coefficient | $I_D$ = 250 $\mu$ A, Referenced to 25°C  |     | <b>-</b> 5          |                      | mV/°C |
| R <sub>DS(on)</sub>                         | Static Drain–Source<br>On–Resistance              | $\begin{split} V_{GS} &= 10 \ V, & I_D = 11 \ A \\ V_{GS} &= 4.5 \ V, & I_D = 10 \ A \\ V_{GS} &= 10 \ V, I_D = 11 \ A, T_J = 125 ^{\circ}C \end{split}$ |     | 9.8<br>12.0<br>13.7 | 12.5<br>17.0<br>22.0 | mΩ    |
| I <sub>D(on)</sub>                          | On-State Drain Current                            | $V_{GS} = 10 \text{ V}, \qquad V_{DS} = 5 \text{ V}$   | 50  |                     |                      | Α     |
| <b>g</b> <sub>FS</sub>                      | Forward Transconductance                          | $V_{DS} = 5 \text{ V}, \qquad I_{D} = 11 \text{ A}$  |     | 48                  |                      | S     |
| Dynamic                                     | Characteristics                                   |  |     |                     |                      |       |
| C <sub>iss</sub>                            | Input Capacitance                                 | $V_{DS} = 15 \text{ V}, \qquad V_{GS} = 0 \text{ V},$  |     | 1205                |                      | pF    |
| C <sub>oss</sub>                            | Output Capacitance                                | f = 1.0 MHz  |     | 290                 |                      | pF    |
| C <sub>rss</sub>                            | Reverse Transfer Capacitance                      | 7  |     | 115                 |                      | pF    |
| R <sub>G</sub>                              | Gate Resistance                                   | V <sub>GS</sub> = 15 mV, f = 1.0 MHz   |     | 2.4                 |                      | Ω     |
| Switchin                                    | g Characteristics (Note 2)                        |  |     |                     |                      |       |
| t <sub>d(on)</sub>                          | Turn-On Delay Time                                | $V_{DD} = 15 \text{ V}, \qquad I_D = 1 \text{ A},$   |     | 9                   | 19                   | ns    |
| t <sub>r</sub>                              | Turn-On Rise Time                                 | $V_{GS} = 10 \text{ V}, \qquad R_{GEN} = 6 \Omega$   |     | 5                   | 10                   | ns    |
| t <sub>d(off)</sub>                         | Turn-Off Delay Time                               |  |     | 28                  | 44                   | ns    |
| t <sub>f</sub>                              | Turn-Off Fall Time                                |  |     | 9                   | 19                   | ns    |
| $Q_g$                                       | Total Gate Charge                                 | $V_{DS} = 15 \text{ V}, \qquad I_{D} = 11 \text{ A},$  |     | 12                  | 16                   | nC    |
| $Q_{gs}$                                    | Gate-Source Charge                                | $V_{GS} = 5 V$   |     | 3.4                 |                      | nC    |
| $Q_{gd}$                                    | Gate-Drain Charge                                 |  |     | 4.0                 |                      | nC    |
| Drain-Sc                                    | ource Diode Characteristics                       | and Maximum Ratings  |     |                     |                      |       |
| Is  | Maximum Continuous Drain-Source                   | e Diode Forward Current  |     |                     | 2.1                  | Α     |
| V <sub>SD</sub>                             | Drain-Source Diode Forward<br>Voltage             | $V_{GS} = 0 \text{ V}, \qquad I_{S} = 2.1 \text{ A (Note 2)}$  |     | 0.74                | 1.2                  | ٧     |
| t <sub>rr</sub>                             | Diode Reverse Recovery Time                       | L 11 A d /d 100 A/us   |     | 24                  |                      | nS    |
| Qrr   | Diode Reverse Recovery Charge                     | $I_F = 11 \text{ A}, d_{iF}/d_t = 100 \text{ A}/\mu\text{s}$   |     | 27                  |                      | nC    |

### Notes:

R<sub>8JA</sub> is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. R<sub>8JC</sub> is guaranteed by design while R<sub>8CA</sub> is determined by the user's board design.



a) 50 °C/W when mounted on a 1in² pad of 2 oz copper



b) 125°C/W when mounted on a minimum pad.

Scale 1 : 1 on letter size paper

2 Test: Pulse Width < 300μs, Duty Cycle < 2.0%
3. Starting TJ = 25 °C, L = 3mH, I<sub>AS</sub> = 8A, V<sub>DD</sub> = 30V, V<sub>GS</sub> = 10V

# **Typical Characteristics**

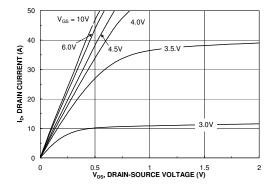


Figure 1. On-Region Characteristics.

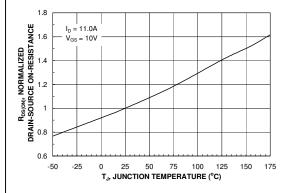


Figure 3. On-Resistance Variation with Temperature.

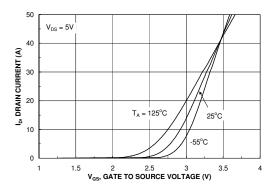


Figure 5. Transfer Characteristics.

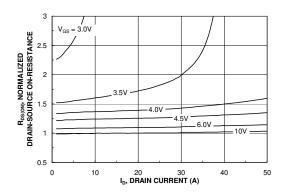


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.

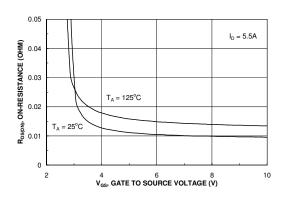


Figure 4. On-Resistance Variation with Gate-to-Source Voltage.

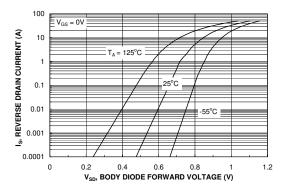
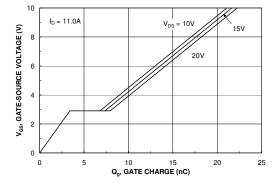


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

# **Typical Characteristics**



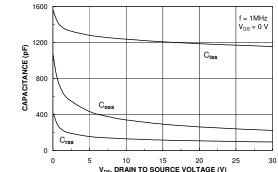


Figure 7. Gate Charge Characteristics.

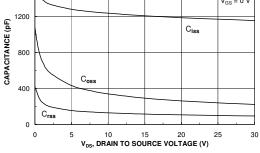
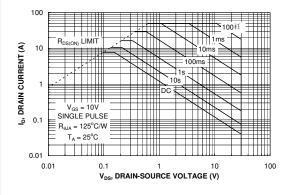


Figure 8. Capacitance Characteristics.



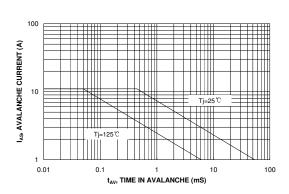
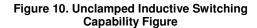


Figure 9. Maximum Safe Operating Area.



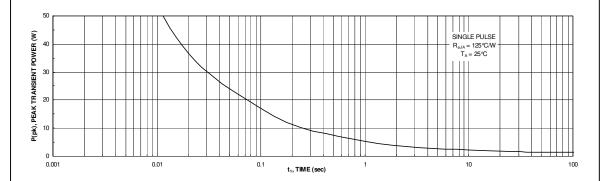


Figure 11. Single Pulse Maximum Power Dissipation.

# **Typical Characteristic**

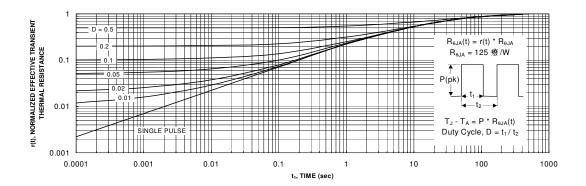


Figure 12. Transient Thermal Response Curve.

Thermal characterization performed using the conditions described in Note 1c. Transient thermal response will change depending on the circuit board design.

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